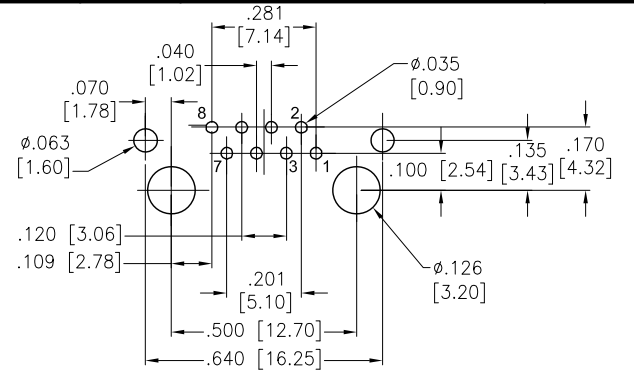
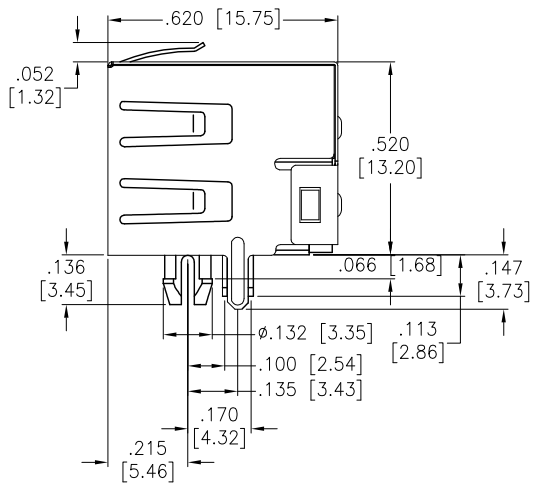
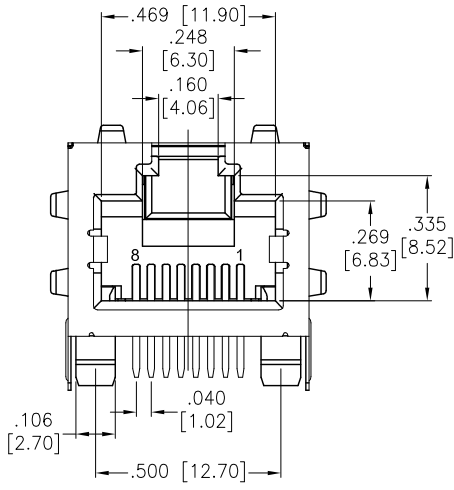


APPROVED: \_\_\_\_\_

DATE: \_\_\_\_\_ TITLE: \_\_\_\_\_

Rev	AWO #	Description	Date	Appr
-	349	Released	1/15/04	
A		REDRAWN	6/26/12	
B		ADDED PANEL CUTOUT AND JACK LOCATION	8/14/12	
C		REVISED HEIGHT DIMENSION	8/21/12	
D		REVISED SHAPE & SPEC.	4/22/14	AY/JL
E		UPDATED SPEC.	4/13/15	HR/LW
F		UPDATED SPEC.	1/15/16	HR/LW
G		UPDATED SPEC.	6/17/16	AY/CH



RECOMMENDED PCB LAYOUT

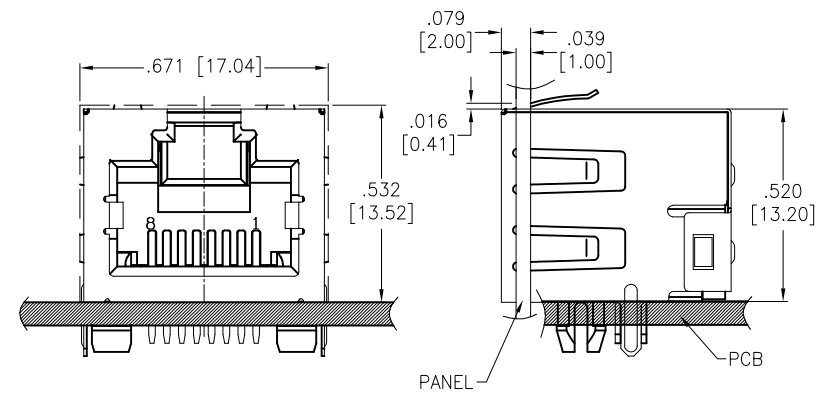
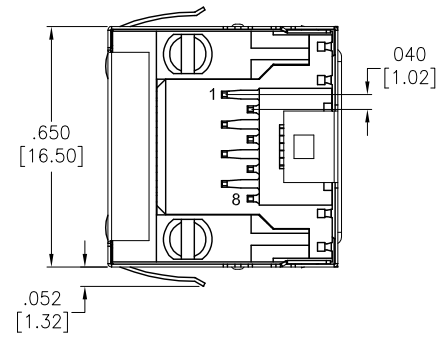
X	PLATING
0	15 µin Gold
1	30 µin Gold
2	50 µin Gold

**SPECIFICATIONS:**

**Material:**  
 Insulator: PBT, glass reinforced, rated UL 94V-0  
 Insulator color: Black  
 Contacts: Phosphor Bronze  
 Shield: Brass, Nickel plated  
 Contacts Plating:  
 Round contact  
 Gold over Nickel underplate overall  
 Flat contact  
 Gold over Nickel underplate on contact area,  
 Tin over Nickel underplate on solder tails  
 (See chart for thickness)

**Electrical:**  
 Voltage rating: 150 VAC rms  
 Current rating: 1.5 Amps max  
 Contact resistance: 20 mohms max. initial  
 Insulation resistance: 1000 Mohms min @ 500 VDC  
 Dielectric withstanding voltage:  
 Contact to Contact: 1,000 VDC or AC Peak for 1 minute  
 Contact to Screen and Test panel: 1,500 VDC or AC Peak for 1 minute

**Temperature Rating:**  
 Operating temperature: -40°C to +85°C  
 Environmental:  
 Lead free, RoHS compliant.



RECOMMENDED PANEL CUTOUT AND JACK LOCATION

UNLESS OTHERWISE SPECIFIED  
 ALL DIMENSIONS ARE MM [INCHES]  
 TOLERANCES: EXCEPT AS NOTED

INCHES		HOLES	
.X	± .10 [2.54]	∅.X	± .10 [2.54]
.XX	± .020 [.51]	∅.XX	± .015 [.38]
.XXX	± .015 [.38]	∅.XXX	± .010 [.25]

APPROVALS		DATE
DRAWN	SLS	8/14/03
CHECKED		
APPROVED		

TITLE: MODULAR TELEPHONE JACK, R/A  
 W/ PANEL GROUNDS

SIZE X	PART NO. MTJ-88ARX1-FSM-PG6	REV. G
REF: S00005C	SCALE: NTS	SHEET 1 OF 1

